504289214 03/24/2017

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT4335895

SUBMISSION TYPE:		NEW ASSIGNMENT	NEW ASSIGNMENT		
NATURE OF CONVEYANCE:		ASSIGNMENT	ASSIGNMENT		
CONVEYING PART	Υ ΟΑΤΑ				
		Name	Execution Date		
BEN PENG XUN			03/14/2017		
FEI LIU	03/14/2017				
MENG MENG GUO	03/14/2017				
HUA TANG			03/14/2017		
HAI FENG YANG			03/14/2017		
Name: Street Address:	CORP	SEMICONDUCTOR MANUFACTURING INTERNATIONAL (SHANGHAI) CORPORATION 18 ZHANGJIANG ROAD, PUDONG NEW AREA			
City:		SHANGHAI			
State/Country:		CHINA			
Postal Code:	201203	201203			
	EPS Total: 1				
PROPERTY NUMB		Number	7		

CORRESPONDENCE DATA

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NAME OF SUBMITTER:	AKIKO YOSHIDA					
SIGNATURE:	/AKIKO YOSHIDA/					
DATE SIGNED:	03/24/2017					
Total Attachments: 3 source=Assignment00158X295#page1.tif						

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PATENT REEL: 041729 FRAME: 0041

ASSIGNMENT AND DECLARATION

WHEREAS I/We, the below named inventor(s) (hereinafter referred to as Assignor(s)) have made an invention entitled:

ASYNCHRONOUS SUCCESSIVE APPROXIMATION REGISTER ANOLOG-TO-DIGITAL CONVERTER CIRCUIT AND METHOD FOR CONFIGURING THE SAME

for which I/We executed an application for United States Letters Patent concurrently herewith or filed an application for United States Letters Patent on ______ (Application No. ______); and

WHEREAS, <u>Semiconductor Manufacturing International (Shanghai) Corporation</u>, a corporation of <u>P. R. China</u> whose post office address is <u>18 Zhangjiang Road</u>, <u>Pudong New Area</u>, <u>Shanghai</u>, <u>China</u> <u>201203</u> (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

AND, I/WE HEREBY covenant that I/We have the full right to convey the interest assigned by this Assignment, and I/We have not executed and will not execute any agreement in conflict with this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me/us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/we have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No.15187,647 filed $_06-20-2016$) the filing date and application number of said application when known.

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Further, as a below named inventor, I hereby declare that:

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the above-identified application, including the claims.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37,Code of Federal Regulations § 1.56, including for continuation-in-part applications, material information which became available between the filing data of the prior application and the national or PCT International filing date of the continuation-in-part application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. §1001 by fine or imprisonment of not more than five (5) years, or both.

IN TESTIMONY WHEREOF, I/We have hereunto set our hands.

Inventor 1 Legal Name:	Ben Peng XUN		_
Signature:	海洋啊.	_ Date:	2017.3.14
Inventor 2 Legal Name:	Fei LIU		
Signature:	A/K	_ Date:	20(7.3.14
Inventor 3 Legal Name:	Meng Meng GUO		
Signature:	- man 10	Date:	2017.3.14

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form or must have been previously filed. Check the box below and complete the attached page(s) to list additional inventors.

____Additional inventors are being named on the ____ supplemental sheet(s) attached hereto.

> `

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SUPPLEMENTAL SHEET FOR DECLARATION AND ASSIGNMENT

ADDITIONAL INVENTOR(S) Supplemental Sheet Page 1 of 1

Inventor 4 Legal Name: Signature: Inventor 5 Legal Name: Signature: Hai Feng YANG Date: 2017.3.14

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